

# ACEPACK DMT-32 modules with SiC power MOSFETs



## Flexible and compact power module for OBC and DC-DC converters



### Best balance between energy losses and high switching frequency operation mode

The ACEPACK DMT-32 dual in-line, molded, through-hole power module is an all-in-one solution for applications in various stages of onboard chargers and auxiliary DC-DC converters in electric and hybrid electric vehicles as well as in solar and energy and motor drive applications.

This compact power module offers flexible topologies ready for implementation in several configurations and a zigzag pinout option allows easier PCB assembly.

Thanks to the DBC substrate, DMT-32 ensures optimal thermal performance, while the fully molded package enhances robustness and reliability, with special grooves designed to improve creepage distance.

#### KEY FEATURES & BENEFITS

- AQS-324 qualified
- 1200 V and 650 V\* breakdown voltage
- SiC MOSFET power switches for higher power density and efficiency
- 175°C maximum junction temperature
- DBC substrate based on AlN to improve thermal performance
- 3.5 kV AC 60 s insulation voltage
- Special grooves on the molded module increase creepage distance

- In-line and zig-zag pinout options
- Integrated NTC sensor

#### KEY APPLICATIONS

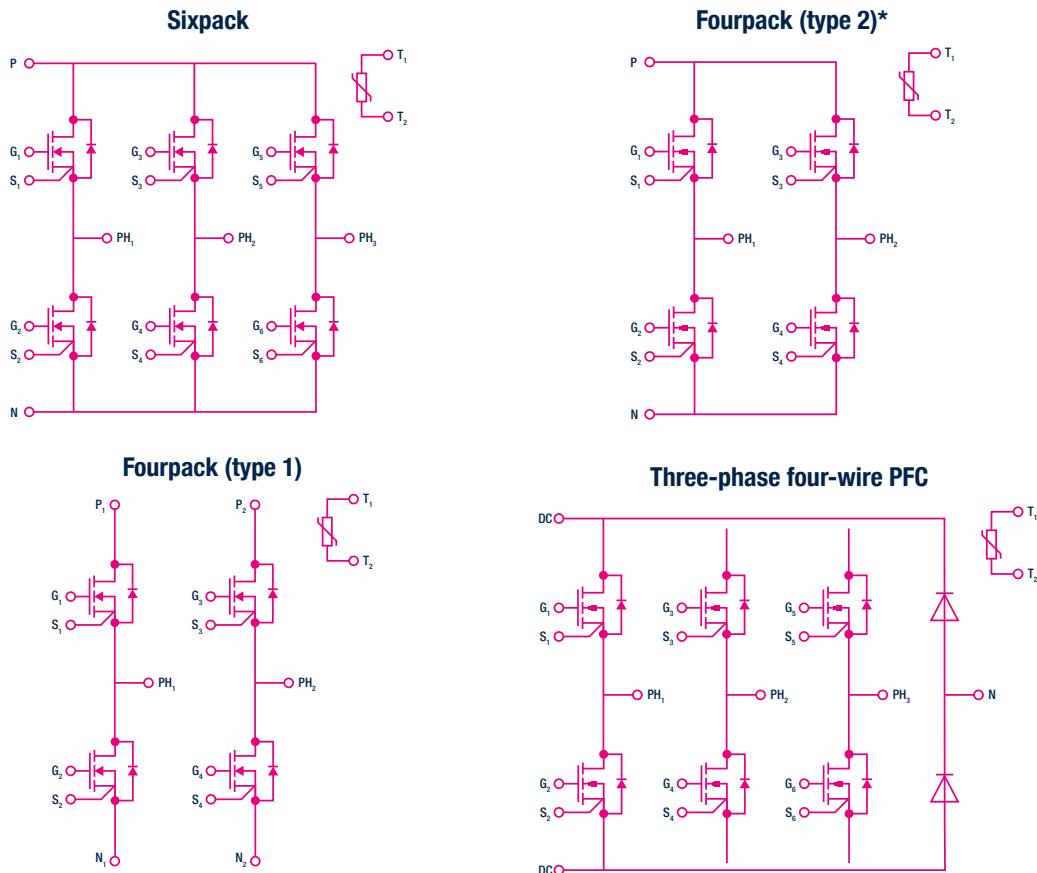
- Onboard charger (OBC)
- DC-DC converter for HEV/EVs
- Fluid pumps
- HVAC
- Active suspensions

(\* ) Under development

The ACEPACK DMT-32 power module incorporates SiC Gen 2 and Gen 3\* MOSFET technology in sixpack, fourpack, and three-phase four-wire PFC converter topologies, helping reduce time to market in applications requiring very high power density and efficiency.

The module range targets different subfunctions from 4 to 22 kW power, and from 650\* to 1200 V voltage rating.

## ACEPACK DMT-32 topologies



(\* Under development)

## Pinout options



## Find out more



© STMicroelectronics - January 2026 - Printed in the United Kingdom - All rights reserved  
ST and the ST logo are registered and/or unregistered trademarks of STMicroelectronics International NV or its affiliates in the EU and/or elsewhere. In particular, ST and the ST logo are Registered in the US Patent and Trademark Office. For additional information about ST trademarks, please refer to [www.st.com/trademarks](http://www.st.com/trademarks). All other product or service names are the property of their respective owners.

